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Patent
Customer No. 006980
Docket No.: GTRC40

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of)
Lu et al.) Group Art Unit: 1712
Serial No.: 09/671,963) Examiner: Sellers, Robert E.
Filed: September 27, 2000)
For: Electrically Conductive Adhesives Having)
Superior Impact Performance)

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DECLARATION

Commissioner for
Patents
Washington, D.C. 20231

Dear Sir:

The undersigned, C.P. Wong, declares and states as follows.

1. My name is C.P. Wong, and I am a co-inventor of the above-referenced patent application.
2. I hold a B.S. degree in chemistry from Purdue University, West Lafayette, IN, and a Ph.D. degree in organic/inorganic chemistry from Pennsylvania State University, University Park.
3. I am a Regents Professor with the School of Materials Science and Engineering and Research Director at the NSF-funded Packaging Research Center, Georgia Institute of Technology, Atlanta.
4. I have published numerous papers in the fields of polymeric materials, high Tc ceramics, materials reaction mechanism, IC encapsulation, in particular, hermetic

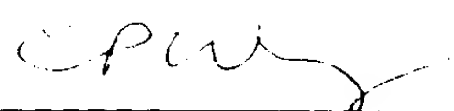
equivalent plastic packaging, electronic manufacturing packaging processes, interfacial adhesions, PWB, SMT assembly, and components reliability.

5. I have received numerous awards including the AT&T Bell Laboratories Distinguished Technical Staff Award in 1987; the AT&T Bell Fellow Award in 1992; the IEEE Components, Packaging and Manufacturing Technology (CPMT) Society Outstanding and Best Paper Awards in 1990, 1991, 1994, 1996, 1998 and 2002; the IEEE Technical Activities Board Distinguished Award in 1994; 1995 IEEE CPMT Society's Outstanding Sustained Technical Contribution Award; the 1999 Georgia Tech's Outstanding Faculty Research Program Development Award; the 1999 NSF-Packaging Research Center Faculty of the Year Award; the 1999 Georgia Tech Sigma Xi Faculty Best Research Paper Award; the University Press (London, UK) Award of Excellence; and was elected a member of the National Academy of Engineering in 2000. I also served as the Technical Vice President (1990 and 1991), and President (1992 and 1993) of the IEEE CPMT Society.

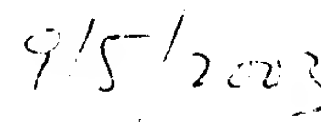
6. I am a co-author of Vincent, M.B., Meyers, L. and Wong, C.P., *Enhancement of underfill performance for flip-chip applications by use of silane additives*, Electronic Components and Technology Conference 1998, 48th IEEE, May 25-28, 1998.

7. I conceived of the work described in Vincent et al., and the work described in Vincent et al. was performed in my laboratory under my direction. Thus, Vincent et al. describes my own work.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statement and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.



C.P. Wong



Date